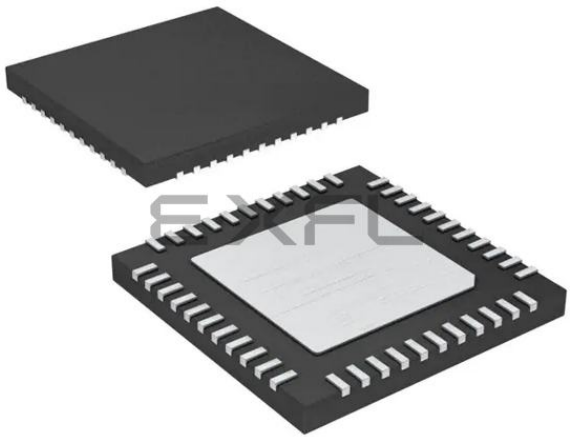

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PSMC, PWM, WDT
Number of I/O	35
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 14x12b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1787t-i-ml

PIC16(L)F178X Family Types

Device	Data Sheet Index	Program Memory Flash (words)	Data EEPROM (bytes)	Data SRAM (bytes)	I/O's(2)	12-bit ADC (ch)	Comparators	Operational Amplifiers	DAC (8/5-bit)	Timers (8/16-bit)	Programmable Switch Mode Controllers (PSMC)	CCP	EUSART	MSSP (I^2C™/SPI)	Debug(1)	XLP
PIC16(L)F1782	(1)	2048	256	256	25	11	3	2	1/0	2/1	2	2	1	1	I	Y
PIC16(L)F1783	(1)	4096	256	512	25	11	3	2	1/0	2/1	2	2	1	1	I	Y
PIC16(L)F1784	(2)	4096	256	512	36	15	4	3	1/0	2/1	3	3	1	1	I	Y
PIC16(L)F1786	(2)	8192	256	1024	25	11	4	2	1/0	2/1	3	3	1	1	I	Y
PIC16(L)F1787	(2)	8192	256	1024	36	15	4	3	1/0	2/1	3	3	1	1	I	Y
PIC16(L)F1788	(3)	16384	256	2048	25	11	4	2	1/3	2/1	4	3	1	1	I	Y
PIC16(L)F1789	(3)	16384	256	2048	36	15	4	3	1/3	2/1	4	3	1	1	I	Y

Note 1: I - Debugging, Integrated on Chip; H - Debugging, available using Debug Header.

2: One pin is input-only.

Data Sheet Index: (Unshaded devices are described in this document.)

1: DS40001579 PIC16(L)F1782/3 Data Sheet, 28-Pin Flash, 8-bit Advanced Analog MCUs.

2: DS40001637 PIC16(L)F1784/6/7 Data Sheet, 28/40/44-Pin Flash, 8-bit Advanced Analog MCUs.

3: DS40001675 PIC16(L)F1788/9 Data Sheet, 28/40/44-Pin Flash, 8-bit Advanced Analog MCUs.

Note: For other small form-factor package availability and marking information, please visit **http://www.microchip.com/packaging** or contact your local sales office.

TABLE 1-2: PIC16(L)F1784/6/7 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RA6/C2OUT(1)/OSC2/ CLKOUT/VCAP	RA6	TTL/ST	CMOS	General purpose I/O.
	C2OUT	—	CMOS	Comparator C2 output.
	OSC2	—	XTAL	Crystal/Resonator (LP, XT, HS modes).
	CLKOUT	—	CMOS	FOSC/4 output.
	VCAP	Power	Power	Filter capacitor for Voltage Regulator.
RA7/PSMC1CLK/PSMC2CLK/ PSMC3CLK/OSC1/CLKIN	RA7	TTL/ST	CMOS	General purpose I/O.
	PSMC1CLK	ST	—	PSMC1 clock input.
	PSMC2CLK	ST	—	PSMC2 clock input.
	PSMC3CLK	ST	—	PSMC3 clock input.
	OSC1	—	XTAL	Crystal/Resonator (LP, XT, HS modes).
	CLKIN	st	—	External clock input (EC mode).
RB0/AN12/C2IN1+/PSMC1IN/ PSMC2IN/PSMC3IN/CCP1(1)/ INT	RB0	TTL/ST	CMOS	General purpose I/O.
	AN12	AN	—	ADC Channel 12 input.
	C2IN1+	AN	—	Comparator C2 positive input.
	PSMC1IN	ST	—	PSMC1 Event Trigger input.
	PSMC2IN	ST	—	PSMC2 Event Trigger input.
	PSMC3IN	ST	—	PSMC3 Event Trigger input.
	CCP1	ST	CMOS	Capture/Compare/PWM1.
	INT	ST	—	External interrupt.
RB1/AN10/C1IN3-/C2IN3-/ C3IN3-/C4IN3-/OPA2OUT	RB1	TTL/ST	CMOS	General purpose I/O.
	AN10	AN	—	ADC Channel 10 input.
	C1IN3-	AN	—	Comparator C1 negative input.
	C2IN3-	AN	—	Comparator C2 negative input.
	C3IN3-	AN	—	Comparator C3 negative input.
	C4IN3-	AN	—	Comparator C4 negative input.
	OPA2OUT	—	AN	Operational Amplifier 2 output.
RB2/AN8/OPA2IN-/CLKR	RB2	TTL/ST	CMOS	General purpose I/O.
	AN8	AN	—	ADC Channel 8 input.
	OPA2IN-	AN	—	Operational Amplifier 2 inverting input.
	CLKR	—	CMOS	Clock output.
RB3/AN9/C1IN2-/C2IN2-/ C3IN2-/OPA2IN+/CCP2(1)	RB3	TTL/ST	CMOS	General purpose I/O.
	AN9	AN	—	ADC Channel 9 input.
	C1IN2-	AN	—	Comparator C1 negative input.
	C2IN2-	AN	—	Comparator C2 negative input.
	C3IN2-	AN	—	Comparator C3 negative input.
	OPA2IN+	AN	—	Operational Amplifier 2 non-inverting input.
	CCP2	ST	CMOS	Capture/Compare/PWM2.
RB4/AN11/C3IN1+	RB4	TTL/ST	CMOS	General purpose I/O.
	AN11	AN	—	ADC Channel 11 input.
	C3IN1+	AN	—	Comparator C3 positive input.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I^2C™ = Schmitt Trigger input with I^2C levels
HV = High Voltage XTAL = Crystal

Note 1: Pin functions can be assigned to one of two locations via software. See ***Register 13-1***.
2: All pins have interrupt-on-change functionality.
3: PIC16(L)F1784/7 only.
4: PIC16(L)F1786 only.

TABLE 3-12: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 31											
F8Ch to FE3h	—	Unimplemented								—	—
FE4h	STATUS_ SHAD	—	—	—	—	—	Z	DC	C	---- -xxx	---- -uuu
FE5h	WREG_SHAD	Working Register Shadow								xxxx xxxx	uuuu uuuu
FE6h	BSR_SHAD	—	—	—	Bank Select Register Shadow					---x xxxx	---u uuuu
FE7h	PCLATH_ SHAD	—	Program Counter Latch High Register Shadow							-xxx xxxx	uuuu uuuu
FE8h	FSR0L_SHAD	Indirect Data Memory Address 0 Low Pointer Shadow								xxxx xxxx	uuuu uuuu
FE9h	FSR0H_ SHAD	Indirect Data Memory Address 0 High Pointer Shadow								xxxx xxxx	uuuu uuuu
FEAh	FSR1L_SHAD	Indirect Data Memory Address 1 Low Pointer Shadow								xxxx xxxx	uuuu uuuu
FEBh	FSR1H_ SHAD	Indirect Data Memory Address 1 High Pointer Shadow								xxxx xxxx	uuuu uuuu
FECh	—	Unimplemented								—	—
FEDh	STKPTR	—	—	—	Current Stack Pointer					---1 1111	---1 1111
FEEh	TOSL	Top of Stack Low byte								xxxx xxxx	uuuu uuuu
FEFh	TOSH	—	Top of Stack High byte							-xxx xxxx	-uuu uuuu

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.

2: Unimplemented, read as '1'.

3: PIC16(L)F1784/7 only.

4: PIC16F1784/6/7 only.

4.2 Register Definitions: Configuration Words

REGISTER 4-1: CONFIG1: CONFIGURATION WORD 1

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
FCMEN	IESO	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		$\overline{\text{CPD}}$
bit 13					bit 8

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		FOSC<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	-n = Value when blank or after Bulk Erase

bit 13 **FCMEN:** Fail-Safe Clock Monitor Enable bit
1 = Fail-Safe Clock Monitor and internal/external switchover are both enabled.
0 = Fail-Safe Clock Monitor is disabled

bit 12 **IESO:** Internal External Switchover bit
1 = Internal/External Switchover mode is enabled
0 = Internal/External Switchover mode is disabled

bit 11 **$\overline{\text{CLKOUTEN}}$:** Clock Out Enable bit
If FOSC configuration bits are set to LP, XT, HS modes:
This bit is ignored, CLKOUT function is disabled. Oscillator function on the CLKOUT pin.
All other FOSC modes:
1 = CLKOUT function is disabled. I/O function on the CLKOUT pin.
0 = CLKOUT function is enabled on the CLKOUT pin

bit 10-9 **BOREN<1:0>:** Brown-out Reset Enable bits
11 = BOR enabled
10 = BOR enabled during operation and disabled in Sleep
01 = BOR controlled by SBOREN bit of the BORCON register
00 = BOR disabled

bit 8 **$\overline{\text{CPD}}$:** Data Code Protection bit(1)
1 = Data memory code protection is disabled
0 = Data memory code protection is enabled

bit 7 **$\overline{\text{CP}}$:** Code Protection bit
1 = Program memory code protection is disabled
0 = Program memory code protection is enabled

bit 6 **MCLRE:** $\overline{\text{MCLR}}$/V_{PP} Pin Function Select bit
If LVP bit = 1:
This bit is ignored.
If LVP bit = 0:
1 = $\overline{\text{MCLR}}$/V_{PP} pin function is $\overline{\text{MCLR}}$; Weak pull-up enabled.
0 = $\overline{\text{MCLR}}$/V_{PP} pin function is digital input; $\overline{\text{MCLR}}$ internally disabled; Weak pull-up under control of WPUE3 bit.

bit 5 **$\overline{\text{PWRTE}}$:** Power-up Timer Enable bit
1 = PWRT disabled
0 = PWRT enabled

bit 4-3 **WDTE<1:0>:** Watchdog Timer Enable bit
11 = WDT enabled
10 = WDT enabled while running and disabled in Sleep
01 = WDT controlled by the SWDTEN bit in the WDTCON register
00 = WDT disabled

4.6 Device ID and Revision ID

The memory location 8006h is where the Device ID and Revision ID are stored. The upper nine bits hold the Device ID. The lower five bits hold the Revision ID. See **Section 12.5 "User ID, Device ID and Configuration Word Access"** for more information on accessing these memory locations.

Development tools, such as device programmers and debuggers, may be used to read the Device ID and Revision ID.

4.7 Register Definitions: Device and Revision

REGISTER 4-3: DEVID: DEVICE ID REGISTER

R	R	R	R	R	R
DEV<8:3>					
bit 13					bit 8

R	R	R	R	R	R	R	R
DEV<2:0>			REV<4:0>				
bit 7							bit 0

Legend:	
R = Readable bit	
'1' = Bit is set	'0' = Bit is cleared

bit 13-5 **DEV<8:0>:** Device ID bits

Device	DEVICEID<13:0> Values	
	DEV<8:0>	REV<4:0>
PIC16F1784	10 1010 010	x xxxx
PIC16LF1784	10 1010 111	x xxxx
PIC16F1786	10 1010 011	x xxxx
PIC16LF1786	10 1011 000	x xxxx
PIC16F1787	10 1010 100	x xxxx
PIC16LF1787	10 1011 001	x xxxx

bit 4-0 **REV<4:0>:** Revision ID bits

These bits are used to identify the revision (see Table under DEV<8:0> above).

6.0 OSCILLATOR MODULE (WITH FAIL-SAFE CLOCK MONITOR)

6.1 Overview

The oscillator module has a wide variety of clock sources and selection features that allow it to be used in a wide range of applications while maximizing performance and minimizing power consumption. Figure 6-1 illustrates a block diagram of the oscillator module.

Clock sources can be supplied from external oscillators, quartz crystal resonators, ceramic resonators and Resistor-Capacitor (RC) circuits. In addition, the system clock source can be supplied from one of two internal oscillators and PLL circuits, with a choice of speeds selectable via software. Additional clock features include:

- Selectable system clock source between external or internal sources via software.
- Two-Speed Start-up mode, which minimizes latency between external oscillator start-up and code execution.
- Fail-Safe Clock Monitor (FSCM) designed to detect a failure of the external clock source (LP, XT, HS, EC or RC modes) and switch automatically to the internal oscillator.
- Oscillator Start-up Timer (OST) ensures stability of crystal oscillator sources

The oscillator module can be configured in one of eight clock modes.

1. ECL – External Clock Low-Power mode (0 MHz to 0.5 MHz)
2. ECM – External Clock Medium-Power mode (0.5 MHz to 4 MHz)
3. ECH – External Clock High-Power mode (4 MHz to 32 MHz)
4. LP – 32 kHz Low-Power Crystal mode.
5. XT – Medium Gain Crystal or Ceramic Resonator Oscillator mode (up to 4 MHz)
6. HS – High Gain Crystal or Ceramic Resonator mode (4 MHz to 20 MHz)
7. RC – External Resistor-Capacitor (RC).
8. INTOSC – Internal oscillator (31 kHz to 32 MHz).

Clock Source modes are selected by the FOSC<2:0> bits in the Configuration Words. The FOSC bits determine the type of oscillator that will be used when the device is first powered.

The EC clock mode relies on an external logic level signal as the device clock source. The LP, XT, and HS clock modes require an external crystal or resonator to be connected to the device. Each mode is optimized for a different frequency range. The RC clock mode requires an external resistor and capacitor to set the oscillator frequency.

The INTOSC internal oscillator block produces low, medium, and high-frequency clock sources, designated LFINTOSC, MFINTOSC and HFINTOSC. (see Internal Oscillator Block, Figure 6-1). A wide selection of device clock frequencies may be derived from these three clock sources.

REGISTER 8-9: PIR4: PERIPHERAL INTERRUPT REQUEST REGISTER 4

U-0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0
—	PSMC3TIF	PSMC2TIF	PSMC1TIF	—	PSMC3SIF	PSMC2SIF	PSMC1SIF
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **Unimplemented:** Read as '0'

bit 6 **PSMC3TIF:** PSMC3 Time Base Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 5 **PSMC2TIF:** PSMC2 Time Base Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 4 **PSMC1TIF:** PSMC1 Time Base Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 3 **Unimplemented:** Read as '0'

bit 2 **PSMC3SIF:** PSMC3 Auto-shutdown Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 1 **PSMC2SIF:** PSMC2 Auto-shutdown Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 0 **PSMC1SIF:** PSMC1 Auto-shutdown Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Enable bit, GIE, of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

EXAMPLE 12-3: FLASH PROGRAM MEMORY READ

```
* This code block will read 1 word of program
* memory at the memory address:
    PROG_ADDR_HI : PROG_ADDR_LO
*   data will be returned in the variables;
*   PROG_DATA_HI, PROG_DATA_LO

    BANKSEL  EEADRL           ; Select Bank for EEPROM registers
    MOVLW    PROG_ADDR_LO     ;
    MOVWF    EEADRL           ; Store LSB of address
    MOVLW    PROG_ADDR_HI     ;
    MOVWL    EEADRH           ; Store MSB of address

    BCF      EECON1,CFGS      ; Do not select Configuration Space
    BSF      EECON1,EEPGD     ; Select Program Memory
    BCF      INTCON,GIE       ; Disable interrupts
    BSF      EECON1,RD        ; Initiate read
    NOP                       ; Executed (Figure 12-1)
    NOP                       ; Ignored (Figure 12-1)
    BSF      INTCON,GIE       ; Restore interrupts

    MOVF     EEDATL,W         ; Get LSB of word
    MOVWF    PROG_DATA_LO     ; Store in user location
    MOVF     EEDATH,W         ; Get MSB of word
    MOVWF    PROG_DATA_HI     ; Store in user location
```

12.6 Write Verify

Depending on the application, good programming practice may dictate that the value written to the data EEPROM or program memory should be verified (see Example 12-7) to the desired value to be written. Example 12-7 shows how to verify a write to EEPROM.

EXAMPLE 12-7: EEPROM WRITE VERIFY

```
BANKSEL EEDATL      ;
MOVF    EEDATL, W   ;EEDATL not changed
                    ;from previous write
BSF     EECON1, RD  ;YES, Read the
                    ;value written
XORWF   EEDATL, W   ;
BTFSS   STATUS, Z   ;Is data the same
GOTO    WRITE_ERR   ;No, handle error
:                   ;Yes, continue
```

13.10 Register Definitions: PORTD

REGISTER 13-26: PORTD: PORTD REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **RD<7:0>**: PORTD General Purpose I/O Pin bits(1)
1 = Port pin is ≥ VIH
0 = Port pin is ≤ VIL

Note 1: Writes to PORTD are actually written to corresponding LATD register. Reads from PORTD register is return of actual I/O pin values.

REGISTER 13-27: TRISD: PORTD TRI-STATE REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **TRISD<7:0>:** PORTD Tri-State Control bits
1 = PORTD pin configured as an input (tri-stated)
0 = PORTD pin configured as an output

REGISTER 13-28: LATD: PORTD DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LATD7	LATD6	LATD5	LATD4	LATD3	LATD2	LATD1	LATD0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **LATD<7:0>**: PORTD Output Latch Value bits(1)

Note 1: Writes to PORTD are actually written to corresponding LATD register. Reads from PORTD register is return of actual I/O pin values.

13.11.7 PORTE FUNCTIONS AND OUTPUT PRIORITIES(1)

Each PORTE pin is multiplexed with other functions. The pins, their combined functions and their output priorities are shown in Table 13-11.

When multiple outputs are enabled, the actual pin control goes to the peripheral with the highest priority.

Analog input and some digital input functions are not included in the list below. These input functions can remain active when the pin is configured as an output. Certain digital input functions override other port functions and are included in the priority list.

Note 1: Applies to 40/44-pin devices only.

TABLE 13-11: PORTE OUTPUT PRIORITY

Pin Name	Function Priority(1)
RE0	CCP3 RE0
RE1	PSMC3B RE1
RE2	PSMC3A RE2

Note 1: Priority listed from highest to lowest.

19.0 DIGITAL-TO-ANALOG CONVERTER (DAC) MODULE

The Digital-to-Analog Converter supplies a variable voltage reference, ratiometric with the input source, with 256 selectable output levels.

The input of the DAC can be connected to:

- External VREF pins
- VDD supply voltage
- FVR (Fixed Voltage Reference)

The output of the DAC can be configured to supply a reference voltage to the following:

- Comparator positive input
- OpAmp positive input
- ADC input channel
- DAC1OUT1 pin
- DAC1OUT2 pin

The Digital-to-Analog Converter (DAC) is enabled by setting the DAC1EN bit of the DAC1CON0 register.

19.1 Output Voltage Selection

The DAC has 256 voltage level ranges. The 256 levels are set with the DAC1R<7:0> bits of the DAC1CON1 register.

The DAC output voltage is determined by Equation 19-1:

EQUATION 19-1: DAC OUTPUT VOLTAGE

IF DACxEN = 1

$$V_{OUT} = \left((V_{SOURCE+} - V_{SOURCE-}) \times \frac{DACxR[7:0]}{2^8} \right) + V_{SOURCE-}$$

VSOURCE+ = VDD, VREF, or FVR BUFFER 2

VSOURCE- = VSS

19.2 Ratiometric Output Level

The DAC output value is derived using a resistor ladder with each end of the ladder tied to a positive and negative voltage reference input source. If the voltage of either input source fluctuates, a similar fluctuation will result in the DAC output value.

The value of the individual resistors within the ladder can be found in **Section 30.0 "Electrical Specifications"**.

19.3 DAC Voltage Reference Output

The DAC voltage can be output to the DAC1OUT1 and DAC1OUT2 pins by setting the respective DAC1OE1 and DAC1OE2 pins of the DAC1CON0 register. Selecting the DAC reference voltage for output on either DAC1OUTx pin automatically overrides the digital output buffer and digital input threshold detector functions of that pin. Reading the DAC1OUTx pin when it has been configured for DAC reference voltage output will always return a '0'.

Due to the limited current drive capability, a buffer must be used on the DAC voltage reference output for external connections to either DAC1OUTx pin. Figure 19-2 shows an example buffering technique.

20.10 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 20-4. Since the analog input pins share their connection with a digital input, they have reverse biased ESD protection diodes to VDD and VSS. The analog input, therefore, must be between VSS and VDD. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up may occur.

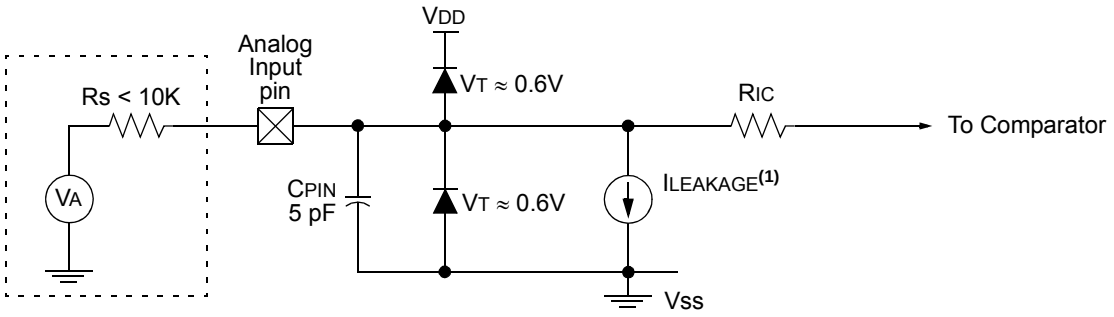
A maximum source impedance of 10 kΩ is recommended for the analog sources. Also, any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current to minimize inaccuracies introduced.

Note 1:	When reading a PORT register, all pins configured as analog inputs will read as a '0'. Pins configured as digital inputs will convert as an analog input, according to the input specification.
2:	Analog levels on any pin defined as a digital input, may cause the input buffer to consume more current than is specified.

20.10.1 ALTERNATE PIN LOCATIONS

This module incorporates I/O pins that can be moved to other locations with the use of the alternate pin function register APFCON. To determine which pins can be moved and what their default locations are upon a Reset, see **Section 13.1 "Alternate Pin Function"** for more information.

FIGURE 20-4: ANALOG INPUT MODEL



Legend: CPIN = Input Capacitance
ILEAKAGE = Leakage Current at the pin due to various junctions
RIC = Interconnect Resistance
RS = Source Impedance
VA = Analog Voltage
VT = Threshold Voltage

Note 1: See **Section 30.0 "Electrical Specifications"**

25.2.6 ALTERNATE PIN LOCATIONS

This module incorporates I/O pins that can be moved to other locations with the use of the alternate pin function register APFCON. To determine which pins can be moved and what their default locations are upon a Reset, see **Section 13.1 "Alternate Pin Function"**for more information.

REGISTER 26-1: SSPSTAT: SSP STATUS REGISTER (CONTINUED)

bit 0 **BF:** Buffer Full Status bit

Receive (SPI and I^2C modes):
1 = Receive complete, SSPBUF is full
0 = Receive not complete, SSPBUF is empty

Transmit (I^2C mode only):
1 = Data transmit in progress (does not include the $\overline{ACK}$ and Stop bits), SSPBUF is full
0 = Data transmit complete (does not include the $\overline{ACK}$ and Stop bits), SSPBUF is empty

TABLE 27-3: BAUD RATE FORMULAS

Configuration Bits			BRG/EUSART Mode	Baud Rate Formula
SYNC	BRG16	BRGH		
0	0	0	8-bit/Asynchronous	FOSC/[64 (n+1)]
0	0	1	8-bit/Asynchronous	FOSC/[16 (n+1)]
0	1	0	16-bit/Asynchronous	
0	1	1	16-bit/Asynchronous	FOSC/[4 (n+1)]
1	0	x	8-bit/Synchronous	
1	1	x	16-bit/Synchronous	

Legend: x = Don't care, n = value of SPBRGH, SPBRGL register pair

TABLE 27-4: SUMMARY OF REGISTERS ASSOCIATED WITH THE BAUD RATE GENERATOR

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BAUDCON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	347
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	346
SPBRGL	BRG<7:0>								348
SPBRGH	BRG<15:8>								348
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	345

Legend: — = unimplemented location, read as '0'. Shaded cells are not used for the Baud Rate Generator.

* Page provides register information.

TABLE 29-4: ENHANCED MID-RANGE INSTRUCTION SET (CONTINUED)

Mnemonic, Operands		Description	Cycles	14-Bit Opcode MSb			LSb	Status Affected	Notes
CONTROL OPERATIONS									
BRA	k	Relative Branch	2	11	001k	kkkk	kkkk		
BRW	–	Relative Branch with W	2	00	0000	0000	1011		
CALL	k	Call Subroutine	2	10	0kkk	kkkk	kkkk		
CALLW	–	Call Subroutine with W	2	00	0000	0000	1010		
GOTO	k	Go to address	2	10	1kkk	kkkk	kkkk		
RETFIE	k	Return from interrupt	2	00	0000	0000	1001		
RETLW	k	Return with literal in W	2	11	0100	kkkk	kkkk		
RETURN	–	Return from Subroutine	2	00	0000	0000	1000		
INHERENT OPERATIONS									
CLRWDT	–	Clear Watchdog Timer	1	00	0000	0110	0100	$\overline{TO}$, $\overline{PD}$	
NOP	–	No Operation	1	00	0000	0000	0000		
OPTION	–	Load OPTION_REG register with W	1	00	0000	0110	0010		
RESET	–	Software device Reset	1	00	0000	0000	0001		
SLEEP	–	Go into Standby mode	1	00	0000	0110	0011	$\overline{TO}$, $\overline{PD}$	
TRIS	f	Load TRIS register with W	1	00	0000	0110	0fff		
C-COMPILER OPTIMIZED									
ADDFSR	n, k	Add Literal k to FSRn	1	11	0001	0nkk	kkkk		
MOVIW	n mm	Move Indirect FSRn to W with pre/post inc/dec modifier, mm	1	00	0000	0001	0nmm	Z	2, 3
	k[n]	Move INDFn to W, Indexed Indirect.	1	11	1111	0nkk	kkkk	Z	2
MOVWI	n mm	Move W to Indirect FSRn with pre/post inc/dec modifier, mm	1	00	0000	0001	1nmm		2, 3
	k[n]	Move W to INDFn, Indexed Indirect.	1	11	1111	1nkk	kkkk		2

Note 1: If the Program Counter (PC) is modified, or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

2: If this instruction addresses an INDF register and the MSb of the corresponding FSR is set, this instruction will require one additional instruction cycle.

3: See Table in the MOVIW and MOVWI instruction descriptions.

29.2 Instruction Descriptions

ADDFSR	Add Literal to FSRn
Syntax:	[*label*] ADDFSR FSRn, k
Operands:	-32 ≤ k ≤ 31 n Î [0, 1]
Operation:	FSR(n) + k → FSR(n)
Status Affected:	None
Description:	The signed 6-bit literal ‘k’ is added to the contents of the FSRnH:FSRnL register pair. FSRn is limited to the range 0000h - FFFFh. Moving beyond these bounds will cause the FSR to wrap-around.

FIGURE 30-5: CLOCK TIMING

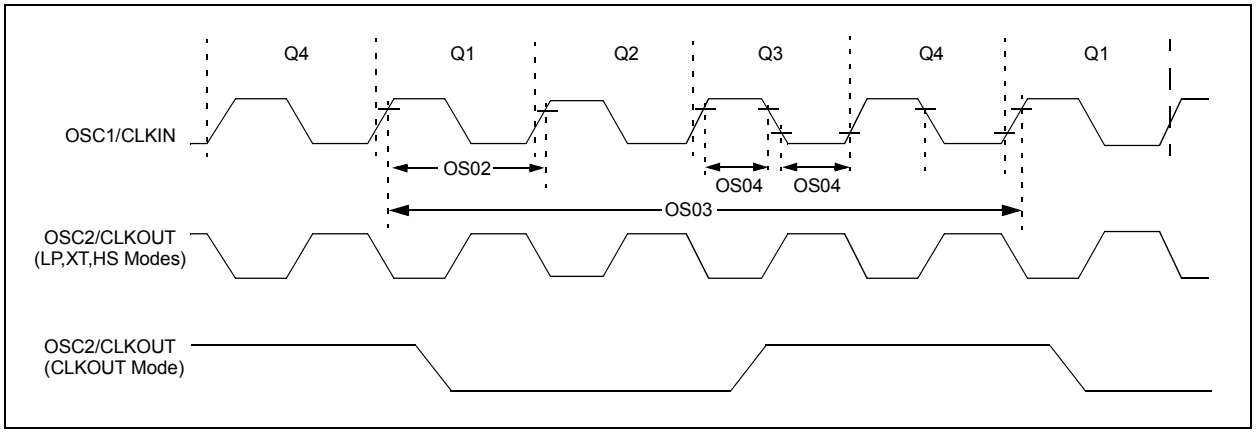


TABLE 30-6: CLOCK OSCILLATOR TIMING REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS01	FOSC	External CLKIN Frequency(1)	DC	—	0.5	MHz	EC Oscillator mode (low)
			DC	—	4	MHz	EC Oscillator mode (medium)
			DC	—	20	MHz	EC Oscillator mode (high)
		Oscillator Frequency(1)	—	32.768	—	kHz	LP Oscillator mode
			0.1	—	4	MHz	XT Oscillator mode
			1	—	4	MHz	HS Oscillator mode
			1	—	20	MHz	HS Oscillator mode, VDD > 2.7V
			DC	—	4	MHz	RC Oscillator mode, VDD > 2.0V
OS02	TOSC	External CLKIN Period(1)	27	—	∞	μs	LP Oscillator mode
			250	—	∞	ns	XT Oscillator mode
			50	—	∞	ns	HS Oscillator mode
			50	—	∞	ns	EC Oscillator mode
		Oscillator Period(1)	—	30.5	—	μs	LP Oscillator mode
			250	—	10,000	ns	XT Oscillator mode
			50	—	1,000	ns	HS Oscillator mode
			250	—	—	ns	RC Oscillator mode
OS03	TCY	Instruction Cycle Time(1)	200	TCY	DC	ns	TCY = 4/FOSC
OS04*	TosH, TosL	External CLKIN High, External CLKIN Low	2	—	—	μs	LP oscillator
			100	—	—	ns	XT oscillator
			20	—	—	ns	HS oscillator
OS05*	TosR, TosF	External CLKIN Rise, External CLKIN Fall	0	—	∞	ns	LP oscillator
			0	—	∞	ns	XT oscillator
			0	—	∞	ns	HS oscillator

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

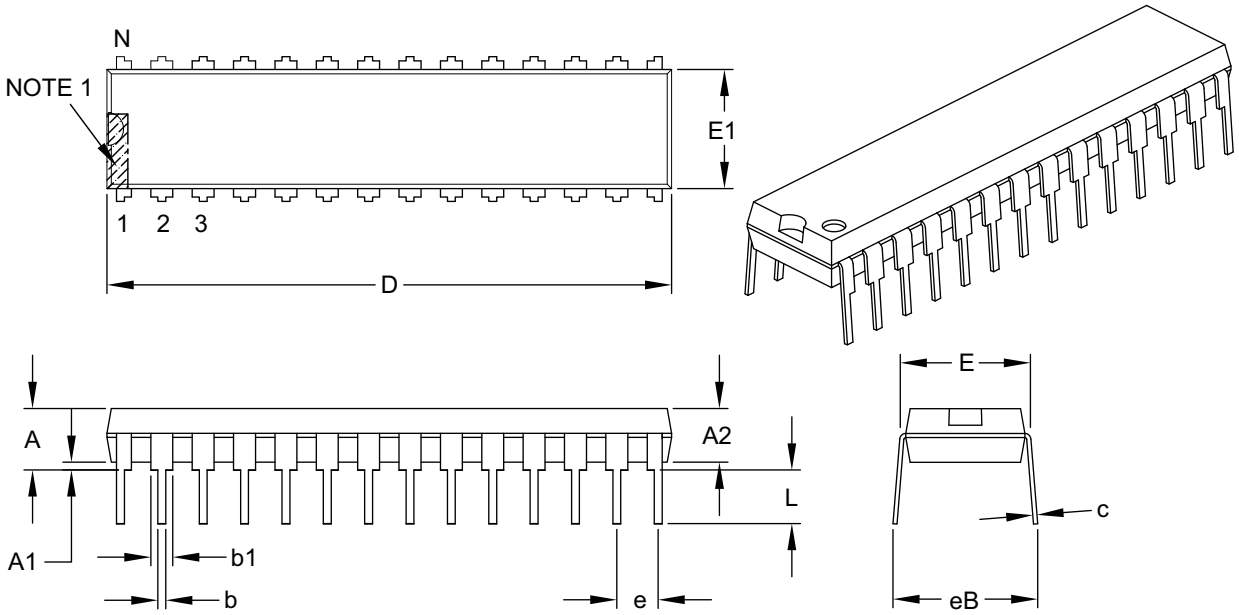
Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to OSC1 pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

33.2 Package Details

The following sections give the technical details of the packages.

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

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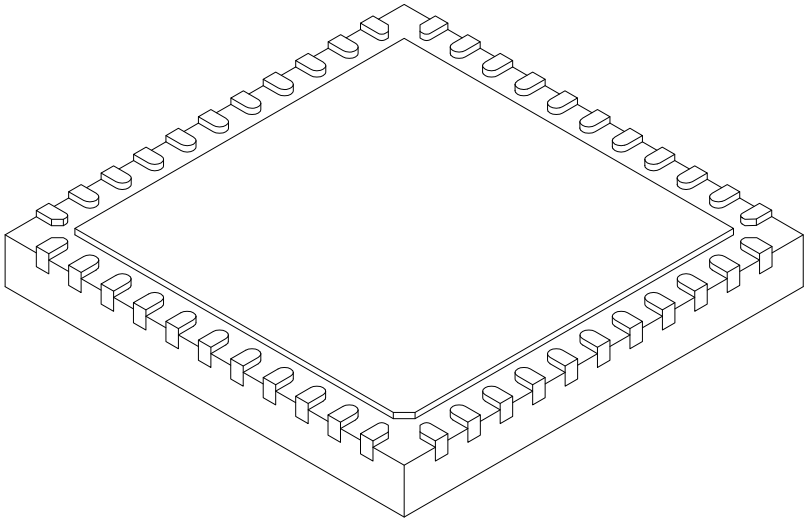
44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.25	6.45	6.60
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.25	6.45	6.60
Terminal Width	b	0.20	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

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